

0,80mm HI-SPEED SOCKET HSECS SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8

Insulator Material: Black Liquid Crystal Polymer Contact: ReCu.

Plating: Au or Šn_over 50μ" (1,27μm) Ni Current Rating: 3.1A @ 30°C Temperature Rise

Operating Temp: -55°C to +125°C

Card Insertion Depth: (3,15mm) .125" nominal RoHS Compliant: Yes

Processing:

Max Processing Temp: 230°C for 60 seconds, or 260°C for 20 seconds 3x Lead-Free Solderable:

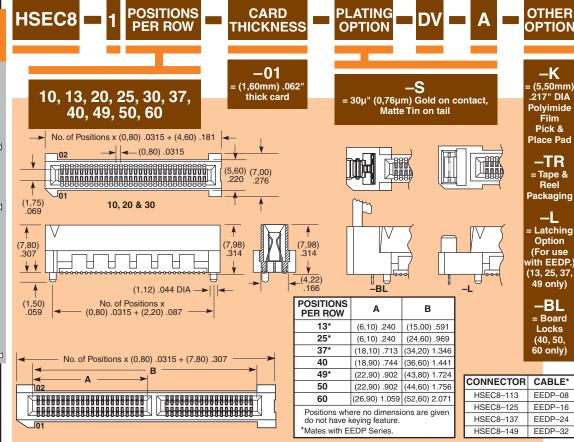
SMT Lead Coplanarity: (0,10mm) .004" max (10-60)

BOARD-TO-BOARD Mates with: APPLICATIONS 1,6mm thick cards, EEDP, HSC8, HSF8 -DV to -DV PCB to -DV IIGH SPEED CABLE & **FLEX APPLICATIONS** 0,80mm HSEC8 Rated @ -3dB Insertion Loss -DV to EEDP 7,98mm Stack Height Single-Ended Signaling 8 GHz / 16 Gbps Alignment 10.5 GHz / 21 Gbps Differential Pair Signaling Pins -DV to HSF8

STANDARD & CUSTOM CARDS AVAILABLE

- · Standard high speed interface cards for 19mm, 25mm & 30mm mated heights, singleended & differential applications. See HSC8 Series.
- · Cards for use with board locks
- Custom cards for low-cost stack height customization
- · Samtec supplied card layout/artwork to make your own cards
- Specialty card shapes

Note: Some lengths, styles and options are non-standard, non-returnable.



Due to technical progress, all designs, specifications and components are subject to change without notice WWW.SAMTEC.COM